

**Guangzhou BDE Technology Inc.**  
**Address: B2-403, Chuangyi Building, 162 Science Avenue, Huangpu District,**  
**Guangzhou 510663, China**

**Office of Engineering Technology**  
**Federal Communications Commission**  
**7435 Oakland Mills Road**  
**Columbia, MD 21046**  
**USA**

Dear Sir/Madam,

We, Guangzhou BDE Technology Inc. Hereby declares the following statement for PHOENIX TESTLAB TAIWAN LTD.,

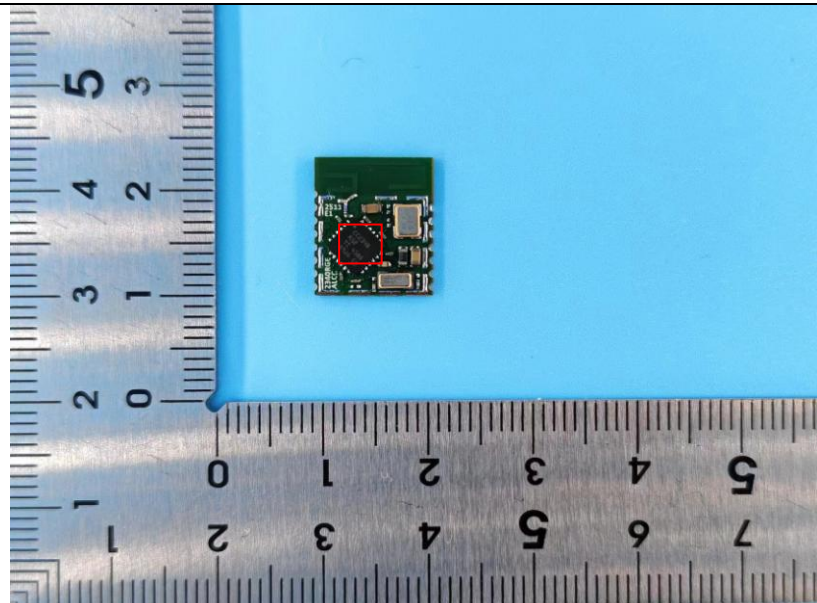
The above models have same PCB board and structure. The difference between the BDE-LE2340R52GEAC and BDE-LE2340R21GEAC models lies in the sizes of their Flash and SRAM of the IC chip. The BDE-LE2340R52GEAC has 512KB of Flash and 36KB of SRAM, while the BDE-LE2340R21GEAC has 256KB of Flash and 28KB of SRAM.

**Product Name: BDE BLE Module Based on CC2340R**

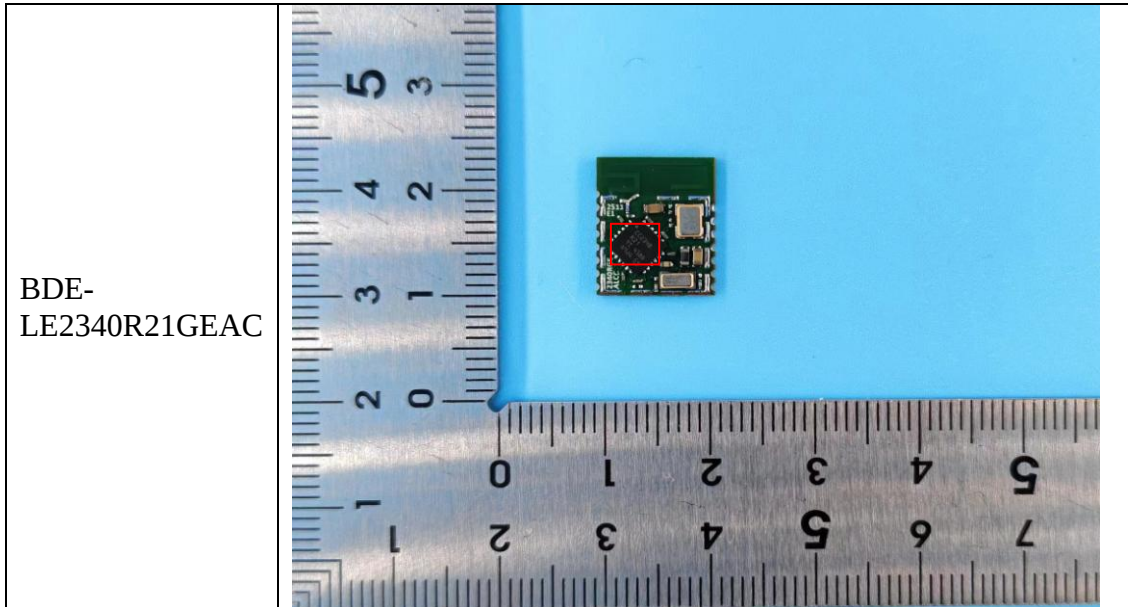
**Trade Mark: BDE**

**Model: BDE-LE2340R52GEAC , BDE-LE2340R21GEAC**

*1, The difference between the BDE-LE2340R52GEAC and BDE-LE2340R21GEAC models lies in the sizes of their Flash and SRAM of the IC chip as following table*

| Model             | difference                                                                           |
|-------------------|--------------------------------------------------------------------------------------|
| BDE-LE2340R52GEAC |  |

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*Jacky Tian*

Signature: \_\_\_\_\_ Date: 2025-7-24

Name: Jacky Tian

Title: CEO

Company: Guangzhou BDE Technology Inc.